

IN THE ABSTRACT

Please amend the Abstract as follows.

Abstract of the Disclosure

A semiconductor integrated circuit device comprises has a semiconductor substrate with squared in plane surface, a plurality of pads disposed over a main surface of the semiconductor substrate along one side thereof of the semiconductor substrate, a. A plurality of input/output cells are disposed corresponding to the plural pads over the main surface of the semiconductor substrate. An, an internal circuit forming section is disposed over the main surface of the semiconductor substrate, and inner than the plural input/output cells, and power Power supply wirings for the internal circuit, for supplying supply potentials to the internal circuit forming section, which are respectively disposed inner than the plural input/output cells. The plural input/output cells include signal cells and power supply cells for internal circuit respectively. The plural pads include signal pads respectively Signal pads are disposed corresponding to the signal cells and electrically connected the signal cells. Power, and power supply pads for the internal circuit are respectively disposed corresponding to the power supply cells and electrically connected to the power supply cells and the power supply wirings. The power supply

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~~pads are disposed closer to the power supply wirings than the signal pads.~~